

ABSTRACT

The present invention provides a phosphazene compound and a photosensitive resin composition, each of which allows water system development and formation of a favorable pattern shape and realizes not only properties such as heat resistance, anti-hydrolysis property, workability (inclusive of solvent solubility) but also photosensitivity, flame retardancy, and sufficient mechanical strength, the phosphazene compound and the photosensitive resin composition being favorably used to produce a wiring substrate which can sufficiently cover smaller and lighter electronic parts of an electronic device. The phosphazene compound according to the present invention is obtained by reacting a phenoxyphosphazene compound (A-1) having a phenolic hydroxyl group and/or a cross-linked phenoxyphosphazene compound (A-2) obtained by cross-linking the phenoxyphosphazene compound (A-1) with an epoxy compound (B) having an unsaturated double bond and/or an isocyanate compound (C), wherein the phosphazene compound has an unsaturated double bond in its molecule. Further, the photosensitive resin composition according to the present invention includes at least: a soluble polyimide resin (G-1), which has a carboxyl group and/or a hydroxyl group and is soluble in an organic solvent, as the

polyimide resins (G); and a phenoxyphosphazene compound (H-1) having a phenolic hydroxyl group and/or a cross-linked phenoxyphosphazene compound (H-2), which is obtained by cross-linking the phenoxyphosphazene compound (H-1) and has at least one phenolic hydroxyl group, as the phosphazene compound (H), and the photosensitive resin composition further includes a (meth)acrylic compound (L).